

# SOT157-2

plastic DIL-bent-SIL power package; 9 leads (lead length 12 mm)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Z (zig-zag)
<b>Package type descriptive code</b>	DBS9P
<b>Package type industry code</b>	DBS9P
<b>Package style descriptive code</b>	DBS (DIL-bent-SIL)
<b>Package style suffix code</b>	P (power)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	12-3-2003

Table 1. Package summary

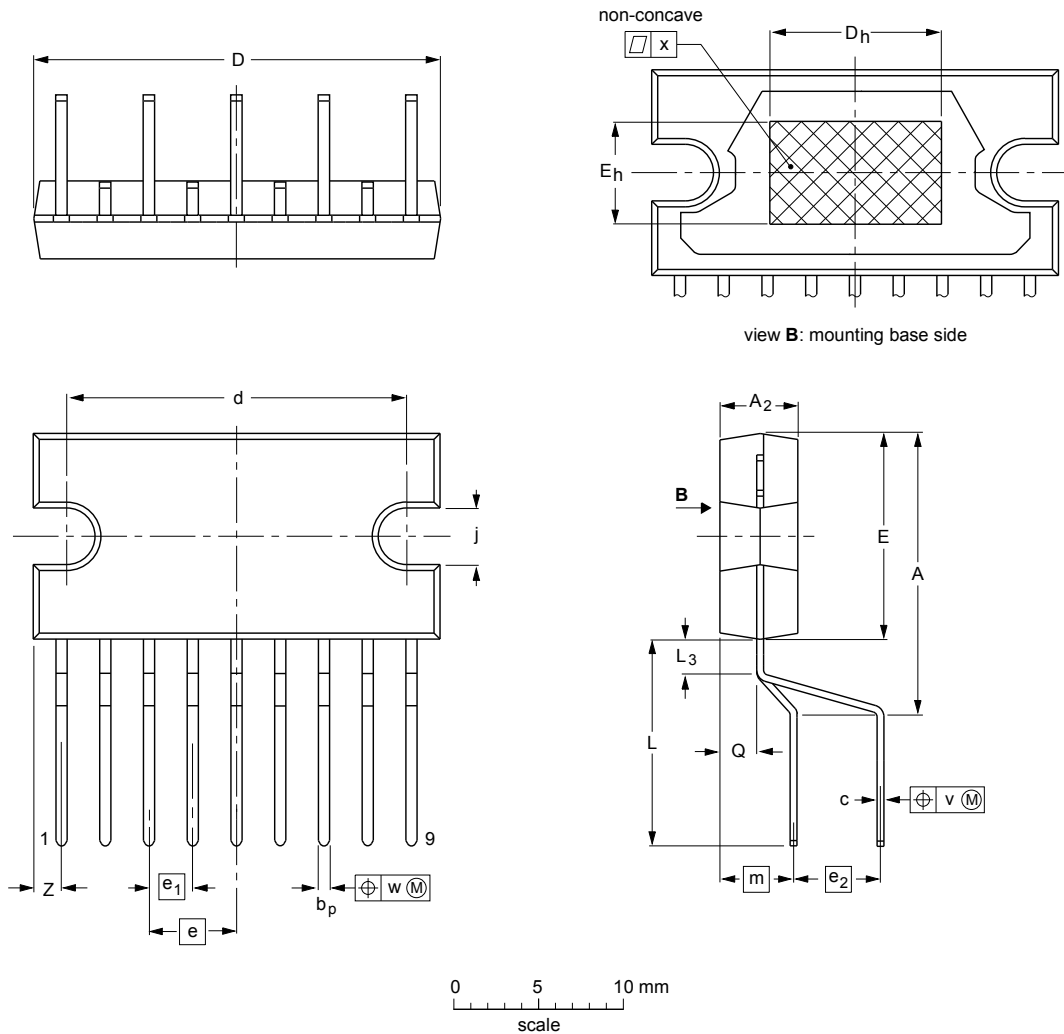
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	23.6	-	23.7	24	mm
E	package width	11.8	-	12	12.2	mm
A	seated height	15.5	-	17	17	mm
A <sub>2</sub>	package height	[tbd]	-	4.4	4.6	mm
n <sub>2</sub>	actual quantity of termination	-	-	9	-	



## 2. Package outline

DBS9P: plastic DIL-bent-SIL power package; 9 leads (lead length 12 mm)

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**DIMENSIONS (mm are the original dimensions)**

UNIT	A	A <sub>2</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	d	D <sub>h</sub>	E <sup>(1)</sup>	e	e <sub>1</sub>	e <sub>2</sub>	E <sub>h</sub>	j	L	L <sub>3</sub>	m	Q	v	w	x	Z <sup>(1)</sup>
mm	17.0 15.5	4.6 4.4	0.75 0.60	0.48 0.38	24.0 23.6	20.0 19.6	10	12.2 11.8	5.08	2.54	5.08	6	3.4 3.1	12.4 11.0	2.4 1.6	4.3	2.1 1.8	0.8	0.25	0.03	2.00 1.45

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT157-2					99-12-17- 03-03-12

Fig. 1. Package outline DBS9P (SOT157-2)

### 3. Legal information

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